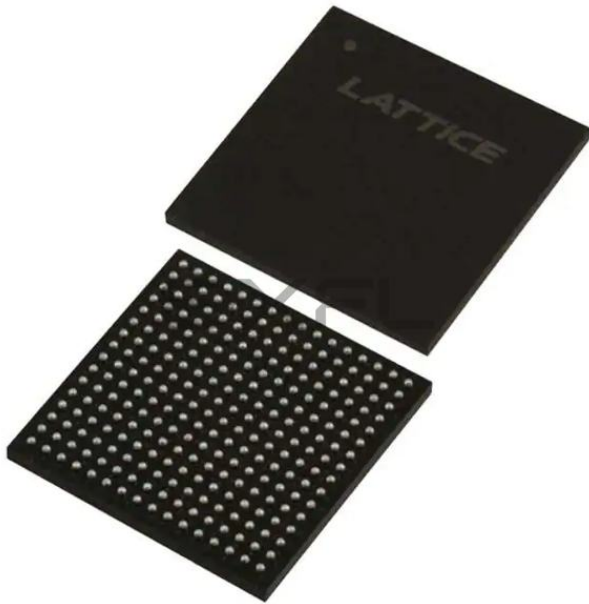




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	3.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	32
Number of Macrocells	512
Number of Gates	-
Number of I/O	208
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-FTBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4512v-35ft256c

Table 2. ispMACH 4000Z Family Selection Guide

	ispMACH 4032ZC	ispMACH 4064ZC	ispMACH 4128ZC	ispMACH 4256ZC
Macrocells	32	64	128	256
I/O + Dedicated Inputs	32+4/32+4	32+4/32+12/ 64+10/64+10	64+10/96+4	64+10/96+6/ 128+4
t _{PD} (ns)	3.5	3.7	4.2	4.5
t _S (ns)	2.2	2.5	2.7	2.9
t _{CO} (ns)	3.0	3.2	3.5	3.8
f _{MAX} (MHz)	267	250	220	200
Supply Voltage (V)	1.8	1.8	1.8	1.8
Max. Standby I _{CC} (μA)	20	25	35	55
Pins/Package	48 TQFP 56 csBGA	48 TQFP 56 csBGA 100 TQFP 132 csBGA	100 TQFP 132csBGA	100 TQFP 132 csBGA 176 TQFP

ispMACH 4000 Introduction

The high performance ispMACH 4000 family from Lattice offers a SuperFAST CPLD solution. The family is a blend of Lattice's two most popular architectures: the ispLSI® 2000 and ispMACH 4A. Retaining the best of both families, the ispMACH 4000 architecture focuses on significant innovations to combine the highest performance with low power in a flexible CPLD family.

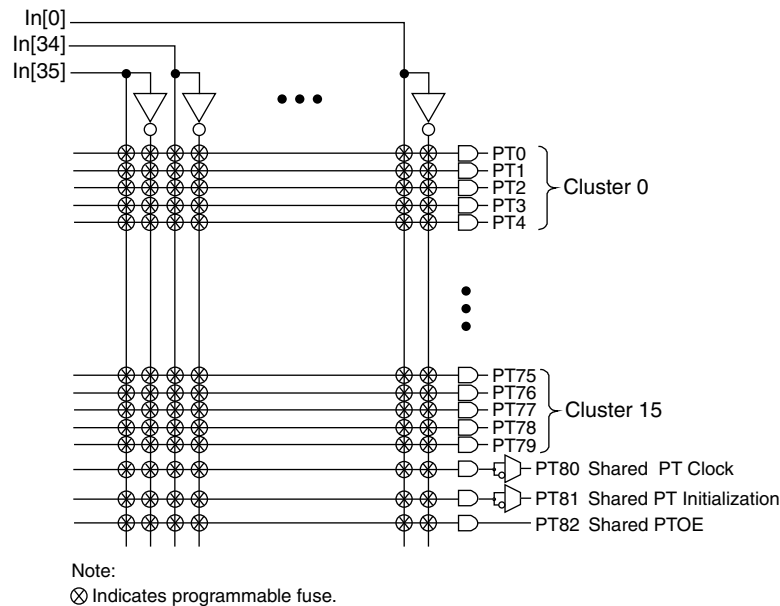
The ispMACH 4000 combines high speed and low power with the flexibility needed for ease of design. With its robust Global Routing Pool and Output Routing Pool, this family delivers excellent First-Time-Fit, timing predictability, routing, pin-out retention and density migration.

The ispMACH 4000 family offers densities ranging from 32 to 512 macrocells. There are multiple density-I/O combinations in Thin Quad Flat Pack (TQFP), Chip Scale BGA (csBGA) and Fine Pitch Thin BGA (ftBGA) packages ranging from 44 to 256 pins/balls. Table 1 shows the macrocell, package and I/O options, along with other key parameters.

The ispMACH 4000 family has enhanced system integration capabilities. It supports 3.3V (4000V), 2.5V (4000B) and 1.8V (4000C/Z) supply voltages and 3.3V, 2.5V and 1.8V interface voltages. Additionally, inputs can be safely driven up to 5.5V when an I/O bank is configured for 3.3V operation, making this family 5V tolerant. The ispMACH 4000 also offers enhanced I/O features such as slew rate control, PCI compatibility, bus-keeper latches, pull-up resistors, pull-down resistors, open drain outputs and hot socketing. The ispMACH 4000 family members are 3.3V/2.5V/1.8V in-system programmable through the IEEE Standard 1532 interface. IEEE Standard 1149.1 boundary scan testing capability also allows product testing on automated test equipment. The 1532 interface signals TCK, TMS, TDI and TDO are referenced to V_{CC} (logic core).

Overview

The ispMACH 4000 devices consist of multiple 36-input, 16-macrocell Generic Logic Blocks (GLBs) interconnected by a Global Routing Pool (GRP). Output Routing Pools (ORPs) connect the GLBs to the I/O Blocks (IOBs), which contain multiple I/O cells. This architecture is shown in Figure 1.

Figure 3. AND Array

Enhanced Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in product term clusters. Each product term cluster is associated with a macrocell. The cluster size for the ispMACH 4000 family is 4+1 (total 5) product terms. The software automatically considers the availability and distribution of product term clusters as it fits the functions within a GLB. The logic allocator is designed to provide three speed paths: 5-PT fast bypass path, 20-PT Speed Locking path and an up to 80-PT path. The availability of these three paths lets designers trade timing variability for increased performance.

The enhanced Logic Allocator of the ispMACH 4000 family consists of the following blocks:

- Product Term Allocator
- Cluster Allocator
- Wide Steering Logic

Figure 4 shows a macrocell slice of the Logic Allocator. There are 16 such slices in the GLB.

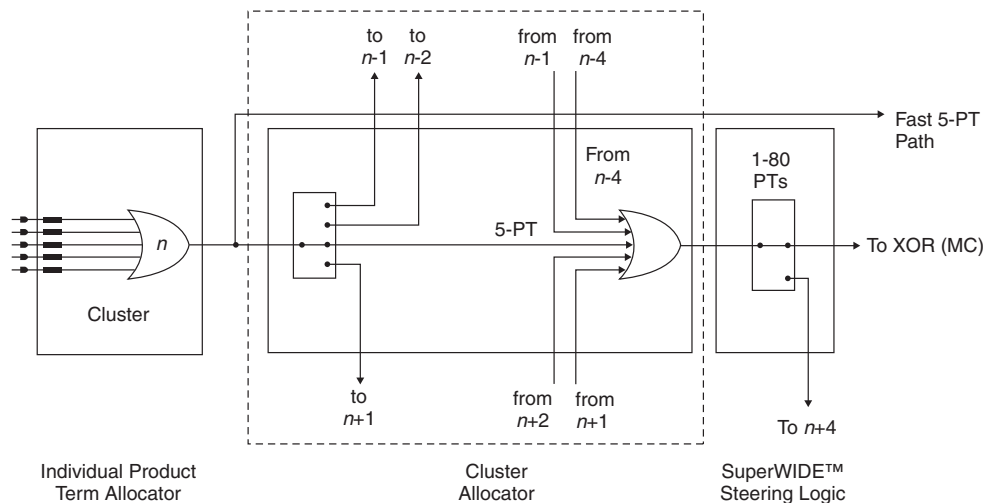
Figure 4. Macrocell Slice

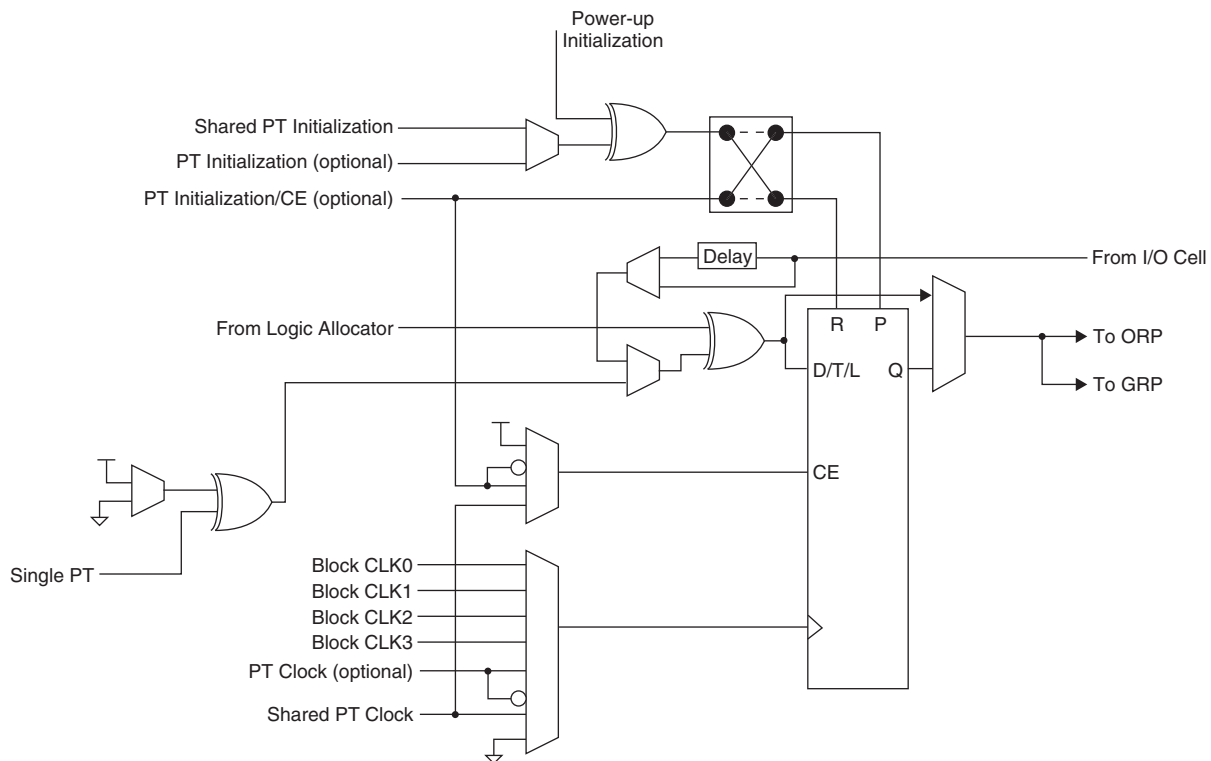
Table 5. Product Term Expansion Capability

Expansion Chains	Macrocells Associated with Expansion Chain (with Wrap Around)	Max PT/Macrocell
Chain-0	M0 M4 M8 M12 M0	75
Chain-1	M1 M5 M9 M13 M1	80
Chain-2	M2 M6 M10 M14 M2	75
Chain-3	M3 M7 M11 M15 M3	70

Every time the super cluster allocator is used, there is an incremental delay of t_{EXP} . When the super cluster allocator is used, all destinations other than the one being steered to, are given the value of ground (i.e., if the super cluster is steered to M (n+4), then M (n) is ground).

Macrocell

The 16 macrocells in the GLB are driven by the 16 outputs from the logic allocator. Each macrocell contains a programmable XOR gate, a programmable register/latch, along with routing for the logic and control functions. Figure 5 shows a graphical representation of the macrocell. The macrocells feed the ORP and GRP. A direct input from the I/O cell allows designers to use the macrocell to construct high-speed input registers. A programmable delay in this path allows designers to choose between the fastest possible set-up time and zero hold time.

Figure 5. Macrocell

Enhanced Clock Multiplexer

The clock input to the flip-flop can select any of the four block clocks along with the shared PT clock, and true and complement forms of the optional individual term clock. An 8:1 multiplexer structure is used to select the clock. The eight sources for the clock multiplexer are as follows:

- Block CLK0
- Block CLK1

Table 7. ORP Combinations for I/O Blocks with 16 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M3, M4, M5, M6, M7, M8, M9, M10
I/O 4	M4, M5, M6, M7, M8, M9, M10, M11
I/O 5	M5, M6, M7, M8, M9, M10, M11, M12
I/O 6	M6, M7, M8, M9, M10, M11, M12, M13
I/O 7	M7, M8, M9, M10, M11, M12, M13, M14
I/O 8	M8, M9, M10, M11, M12, M13, M14, M15
I/O 9	M9, M10, M11, M12, M13, M14, M15, M0
I/O 10	M10, M11, M12, M13, M14, M15, M0, M1
I/O 11	M11, M12, M13, M14, M15, M0, M1, M2
I/O 12	M12, M13, M14, M15, M0, M1, M2, M3
I/O 13	M13, M14, M15, M0, M1, M2, M3, M4
I/O 14	M14, M15, M0, M1, M2, M3, M4, M5
I/O 15	M15, M0, M1, M2, M3, M4, M5, M6

Table 8. ORP Combinations for I/O Blocks with 4 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M4, M5, M6, M7, M8, M9, M10, M11
I/O 2	M8, M9, M10, M11, M12, M13, M14, M15
I/O 3	M12, M13, M14, M15, M0, M1, M2, M3

Table 9. ORP Combinations for I/O Blocks with 10 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5
I/O 8	M2, M3, M4, M5, M6, M7, M8, M9
I/O 9	M10, M11, M12, M13, M14, M15, M0, M1

Table 10. ORP Combinations for I/O Blocks with 12 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M4, M5, M6, M7, M8, M9, M10, M11
I/O 4	M5, M6, M7, M8, M9, M10, M11, M12
I/O 5	M6, M7, M8, M9, M10, M11, M12, M13
I/O 6	M8, M9, M10, M11, M12, M13, M14, M15
I/O 7	M9, M10, M11, M12, M13, M14, M15, M0
I/O 8	M10, M11, M12, M13, M14, M15, M0, M1
I/O 9	M12, M13, M14, M15, M0, M1, M2, M3
I/O 10	M13, M14, M15, M0, M1, M2, M3, M4
I/O 11	M14, M15, M0, M1, M2, M3, M4, M5

ORP Bypass and Fast Output Multiplexers

The ORP bypass and fast-path output multiplexer is a 4:1 multiplexer and allows the 5-PT fast path to bypass the ORP and be connected directly to the pin with either the regular output or the inverted output. This multiplexer also allows the register output to bypass the ORP to achieve faster t_{CO} .

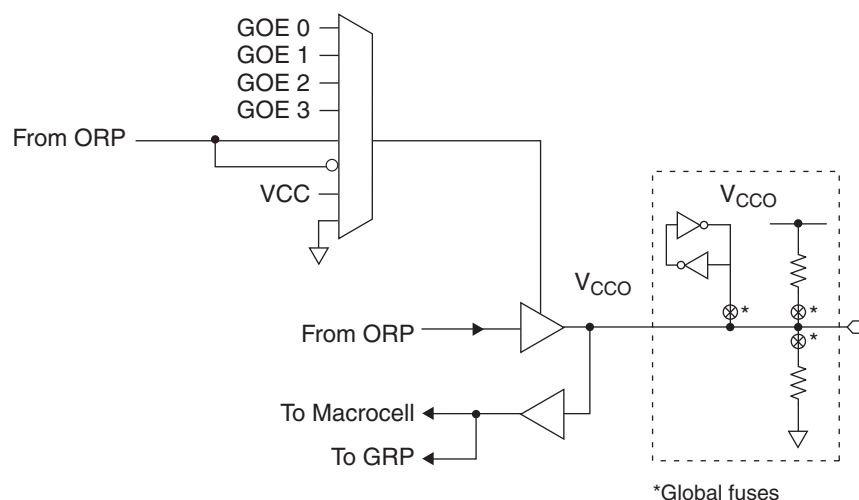
Output Enable Routing Multiplexers

The OE Routing Pool provides the corresponding local output enable (OE) product term to the I/O cell.

I/O Cell

The I/O cell contains the following programmable elements: output buffer, input buffer, OE multiplexer and bus maintenance circuitry. Figure 8 details the I/O cell.

Figure 8. I/O Cell



Each output supports a variety of output standards dependent on the V_{CCO} supplied to its I/O bank. Outputs can also be configured for open drain operation. Each input can be programmed to support a variety of standards, independent of the V_{CCO} supplied to its I/O bank. The I/O standards supported are:

- LVTTTL
- LVCMOS 3.3
- LVCMOS 2.5
- LVCMOS 1.8
- 3.3V PCI Compatible

All of the I/Os and dedicated inputs have the capability to provide a bus-keeper latch, Pull-up Resistor or Pull-down Resistor. A fourth option is to provide none of these. The selection is done on a global basis. The default in both hardware and software is such that when the device is erased or if the user does not specify, the input structure is configured to be a Pull-up Resistor.

Each ispMACH 4000 device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for fast slew or slow slew. The typical edge rate difference between fast and slow slew setting is 20%. For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed.

Global OE Generation

Most ispMACH 4000 family devices have a 4-bit wide Global OE Bus, except the ispMACH 4032 device that has a 2-bit wide Global OE Bus. This bus is derived from a 4-bit internal global OE PT bus and two dual purpose I/O or GOE pins. Each signal that drives the bus can optionally be inverted.

Each GLB has a block-level OE PT that connects to all bits of the Global OE PT bus with four fuses. Hence, for a 256-macrocell device (with 16 blocks), each line of the bus is driven from 16 OE product terms. Figures 9 and 10 show a graphical representation of the global OE generation.

Figure 9. Global OE Generation for All Devices Except ispMACH 4032

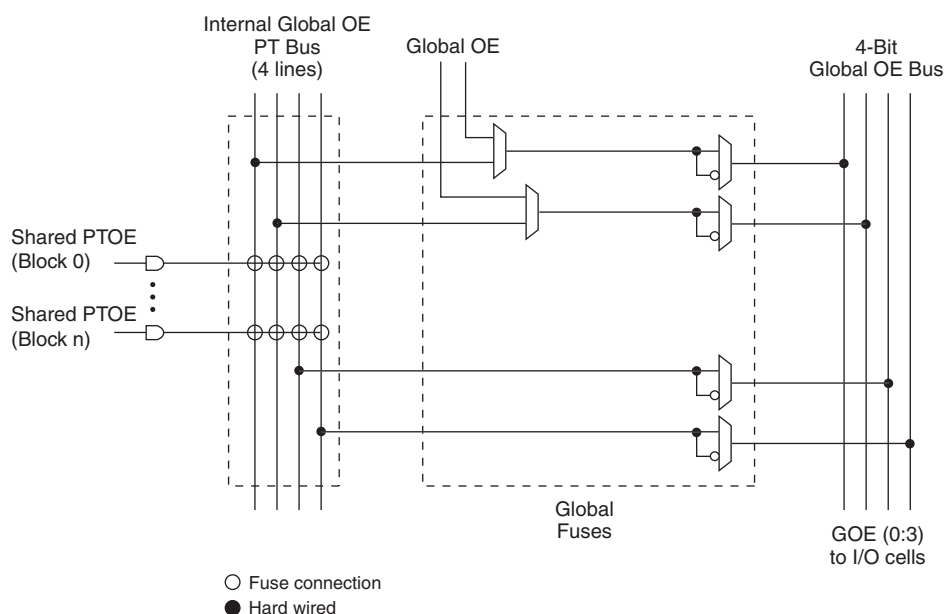
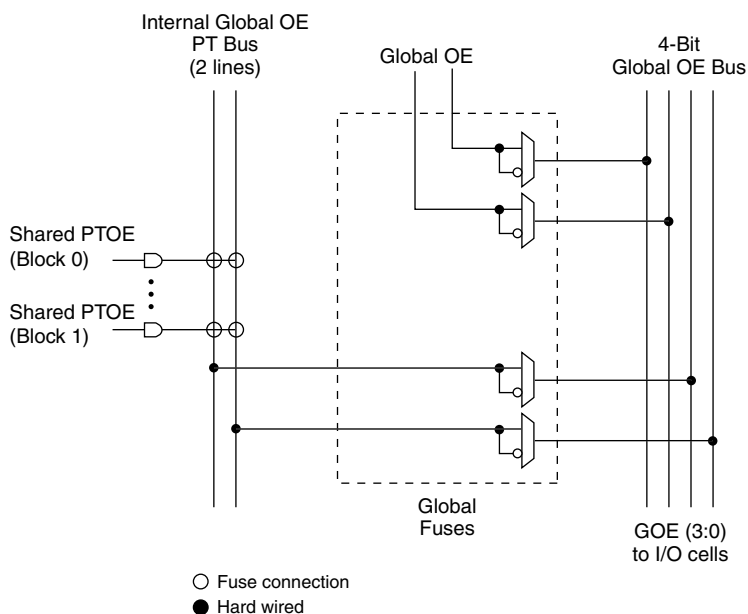


Figure 10. Global OE Generation for ispMACH 4032

Zero Power/Low Power and Power Management

The ispMACH 4000 family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced E^2 low power cell and non sense-amplifier design approach (full CMOS logic approach), the ispMACH 4000 family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

The zero power ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the ispMACH 4000Z family is able to achieve the industry’s “lowest static power”.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 4000 devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os’ physical nature should be minimal so that board test time is minimized. The ispMACH 4000 family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice’s ispVM® System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

Supply Current, ispMACH 4000V/B/C

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4032V/B/C						
ICC ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	11.8	—	mA
		Vcc = 2.5V	—	11.8	—	mA
		Vcc = 1.8V	—	1.8	—	mA
ICC ⁴	Standby Power Supply Current	Vcc = 3.3V	—	11.3	—	mA
		Vcc = 2.5V	—	11.3	—	mA
		Vcc = 1.8V	—	1.3	—	mA
ispMACH 4064V/B/C						
ICC ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
ICC ⁵	Standby Power Supply Current	Vcc = 3.3V	—	11.5	—	mA
		Vcc = 2.5V	—	11.5	—	mA
		Vcc = 1.8V	—	1.5	—	mA
ispMACH 4128V/B/C						
ICC ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
ICC ⁴	Standby Power Supply Current	Vcc = 3.3V	—	11.5	—	mA
		Vcc = 2.5V	—	11.5	—	mA
		Vcc = 1.8V	—	1.5	—	mA
ispMACH 4256V/B/C						
I _{CC} ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	12.5	—	mA
		Vcc = 2.5V	—	12.5	—	mA
		Vcc = 1.8V	—	2.5	—	mA
I _{CC} ⁴	Standby Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
ispMACH 4384V/B/C						
I _{CC} ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	13.5	—	mA
		Vcc = 2.5V	—	13.5	—	mA
		Vcc = 1.8V	—	3.5	—	mA
I _{CC} ⁴	Standby Power Supply Current	Vcc = 3.3V	—	12.5	—	mA
		Vcc = 2.5V	—	12.5	—	mA
		Vcc = 1.8V	—	2.5	—	mA
ispMACH 4512V/B/C						
I _{CC} ^{1,2,3}	Operating Power Supply Current	Vcc = 3.3V	—	14	—	mA
		Vcc = 2.5V	—	14	—	mA
		Vcc = 1.8V	—	4	—	mA

Supply Current, ispMACH 4000Z (Cont.)

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
ispMACH 4256ZC						
ICC ^{1, 2, 3, 5}	Operating Power Supply Current	V _{CC} = 1.8V, T _A = 25°C	—	341	—	μA
		V _{CC} = 1.9V, T _A = 70°C	—	361	—	μA
		V _{CC} = 1.9V, T _A = 85°C	—	372	—	μA
		V _{CC} = 1.9V, T _A = 125°C	—	468	—	μA
ICC ^{4, 5}	Standby Power Supply Current	V _{CC} = 1.8V, T _A = 25°C	—	13	—	μA
		V _{CC} = 1.9V, T _A = 70°C	—	32	55	μA
		V _{CC} = 1.9V, T _A = 85°C	—	43	90	μA
		V _{CC} = 1.9V, T _A = 125°C	—	135	—	μA

1. T_A = 25°C, frequency = 1.0 MHz.

2. Device configured with 16-bit counters.

3. I_{CC} varies with specific device configuration and operating frequency.

4. V_{CCO} = 3.6V, V_{IN} = 0V or V_{CCO}, bus maintenance turned off. V_{IN} above V_{CCO} will add transient current above the specified standby I_{CC}.

5. Includes V_{CCO} current without output loading.

ispMACH 4000V/B/C Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
In/Out Delays								
t _{IN}	Input Buffer Delay	—	0.95	—	1.50	—	2.00	ns
t _{GOE}	Global OE Pin Delay	—	4.04	—	6.04	—	7.04	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	1.83	—	2.28	—	3.28	ns
t _{BUF}	Delay through Output Buffer	—	1.00	—	1.50	—	1.50	ns
t _{EN}	Output Enable Time	—	0.96	—	0.96	—	0.96	ns
t _{DIS}	Output Disable Time	—	0.96	—	0.96	—	0.96	ns
Routing/GLB Delays								
t _{ROUTE}	Delay through GRP	—	1.51	—	2.26	—	3.26	ns
t _{MCELL}	Macrocell Delay	—	1.05	—	1.45	—	1.95	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	0.56	—	0.96	—	1.46	ns
t _{FBK}	Internal Feedback Delay	—	0.00	—	0.00	—	0.00	ns
t _{PDb}	5-PT Bypass Propagation Delay	—	1.54	—	2.24	—	3.24	ns
t _{PDi}	Macrocell Propagation Delay	—	0.94	—	1.24	—	1.74	ns
Register/Latch Delays								
t _S	D-Register Setup Time (Global Clock)	1.32	—	1.57	—	1.57	—	ns
t _{S_PT}	D-Register Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _{ST}	T-Register Setup Time (Global Clock)	1.52	—	1.77	—	1.77	—	ns
t _{ST_PT}	T-Register Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _H	D-Register Hold Time	1.68	—	2.93	—	3.93	—	ns
t _{HT}	T-Register Hold Time	1.68	—	2.93	—	3.93	—	ns
t _{SIR}	D-Input Register Setup Time (Global Clock)	1.52	—	1.57	—	1.57	—	ns
t _{SIR_PT}	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
t _{HIR}	D-Input Register Hold Time (Global Clock)	0.68	—	1.18	—	1.18	—	ns
t _{HIR_PT}	D-Input Register Hold Time (Product Term Clock)	0.68	—	1.18	—	1.18	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	0.52	—	0.67	—	1.17	ns
t _{CES}	Clock Enable Setup Time	2.25	—	2.25	—	2.25	—	ns
t _{CEH}	Clock Enable Hold Time	1.88	—	1.88	—	1.88	—	ns
t _{SL}	Latch Setup Time (Global Clock)	1.32	—	1.57	—	1.57	—	ns
t _{SL_PT}	Latch Setup Time (Product Term Clock)	1.32	—	1.32	—	1.32	—	ns
t _{HL}	Latch Hold Time	1.17	—	1.17	—	1.17	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/ Feedback MUX	—	0.25	—	0.25	—	0.25	ns
t _{SRI}	Asynchronous Reset or Set to Output/Feedback MUX Delay	0.28	—	0.28	—	0.28	—	ns
t _{SRR}	Asynchronous Reset or Set Recovery Time	1.67	—	1.67	—	1.67	—	ns
Control Delays								
t _{BCLK}	GLB PT Clock Delay	—	1.12	—	1.12	—	0.62	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	0.87	—	0.87	—	0.87	ns
t _{BSR}	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
t _{PTSR}	Macrocell PT Set/Reset Delay	—	2.51	—	3.41	—	3.41	ns

Signal Descriptions

Signal Names	Description
TMS	Input – This pin is the IEEE 1149.1 Test Mode Select input, which is used to control the state machine.
TCK	Input – This pin is the IEEE 1149.1 Test Clock input pin, used to clock through the state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data In pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data Out pin used to shift data out.
GOE0/IO, GOE1/IO	These pins are configured to be either Global Output Enable Input or as general I/O pins.
GND	Ground
NC	Not Connected
V _{CC}	The power supply pins for logic core and JTAG port.
CLK0/I, CLK1/I, CLK2/I, CLK3/I	These pins are configured to be either CLK input or as an input.
V _{CC00} , V _{CC01}	The power supply pins for each I/O bank.
yzz	Input/Output ¹ – These are the general purpose I/O used by the logic array. y is GLB reference (alpha) and z is macrocell reference (numeric). z: 0-15.
	ispMACH 4032 y: A-B
	ispMACH 4064 y: A-D
	ispMACH 4128 y: A-H
	ispMACH 4256 y: A-P
	ispMACH 4384 y: A-P, AX-HX
	ispMACH 4512 y: A-P, AX-PX

1. In some packages, certain I/Os are only available for use as inputs. See the signal connections table for details.

ispMACH 4000V/B/C ORP Reference Table

	4032V/B/C		4064V/B/C			4128V/B/C			4256V/B/C				4384V/B/C		4512V/B/C	
Number of I/Os	30 ¹	32	30 ²	32	64	64	92 ³	96	64	96 ⁴	128	160	128	192	128	208
Number of GLBs	2	2	4	4	4	8	8	8	16	16	16	16	16	16	16	16
Number of I/Os / GLB	16	16	8	8	16	8	12	12	4	8	8	10	8	8	8	Mixture of 8 & 4 ⁵
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB		4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB	10 I/Os / GLB	8 I/Os / GLB		8 I/Os / GLB	8 I/Os / GLB 4 I/Os / GLB

1. 32-macrocell device, 44 TQFP: 2 GLBs have 15 out of 16 I/Os bonded out.

2. 64-macrocells device, 44 TQFP: 2 GLBs have 7 out of 8 I/Os bonded out.

3. 128-macrocell device, 128 TQFP: 4 GLBs have 11 out of 12 I/Os

4. 256-macrocell device, 144 TQFP: 16 GLBs have 6 I/Os per

5. 512-macrocell device: 20 GLBs have 8 I/Os per, 12 GLBs have 4 I/Os per

ispMACH 4000Z ORP Reference Table

	4032Z	4064Z		4128Z		4256Z		
Number of I/Os	32	32	64	64	96	64	96 ¹	128
Number of GLBs	2	4	4	8	8	16	16	16
Number of I/Os / GLB	16	8	16	8	12	4	8	8
Reference ORP Table	16 I/Os / GLB	8 I/Os / GLB	16 I/Os / GLB	8 I/Os / GLB	12 I/Os / GLB	4 I/Os / GLB	8 I/Os / GLB	8 I/Os / GLB

1. 256-macrocell device, 132 csBGA: 16 GLBs have 6 I/Os per

**ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections:
44-Pin TQFP**

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A ⁵	A10	A ⁵
3	0	A6	A ⁶	A12	A ⁶
4	0	A7	A ⁷	A14	A ⁷
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A ⁸	B0	B ⁰
8	0	A9	A ⁹	B2	B ¹
9	0	A10	A ¹⁰	B4	B ²
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A ¹²	B8	B ⁴
14	0	A13	A ¹³	B10	B ⁵
15	0	A14	A ¹⁴	B12	B ⁶
16	0	A15	A ¹⁵	B14	B ⁷
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B ⁰	C0	C ⁰
19	1	B1	B ¹	C2	C ¹
20	1	B2	B ²	C4	C ²
21	1	B3	B ³	C6	C ³
22	1	B4	B ⁴	C8	C ⁴
23	-	TMS	-	TMS	-
24	1	B5	B ⁵	C10	C ⁵
25	1	B6	B ⁶	C12	C ⁶
26	1	B7	B ⁷	C14	C ⁷
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B ⁸	D0	D ⁰
30	1	B9	B ⁹	D2	D ¹
31	1	B10	B ¹⁰	D4	D ²
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B ¹²	D8	D ⁴
36	1	B13	B ¹³	D10	D ⁵
37	1	B14	B ¹⁴	D12	D ⁶
38	1	B15/GOE1	B ¹⁵	D14/GOE1	D ⁷
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A ⁰	A0/GOE0	A ⁰
41	0	A1	A ¹	A2	A ¹

**ispMACH 4064V/B/C/Z, 4128V/B/C/Z, 4256V/B/C/Z Logic Signal Connections:
100-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4064V/B/C/Z		ispMACH 4128V/B/C/Z		ispMACH 4256V/B/C/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
83	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
84	1	D3	D ³	H6	H ³	P12	P ³
85	1	D2	D ²	H4	H ²	P10	P ²
86	1	D1	D ¹	H2	H ¹	P6	P ¹
87	1	D0/GOE1	D ⁰	H0/GOE1	H ⁰	P2/OE1	P ⁰
88	1	CLK3/I	-	CLK3/I	-	CLK3/I	-
89	0	CLK0/I	-	CLK0/I	-	CLK0/I	-
90	-	VCC	-	VCC	-	VCC	-
91	0	A0/GOE0	A ⁰	A0/GOE0	A ⁰	A2/GOE0	A ⁰
92	0	A1	A ¹	A2	A ¹	A6	A ¹
93	0	A2	A ²	A4	A ²	A10	A ²
94	0	A3	A ³	A6	A ³	A12	A ³
95	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
96	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
97	0	A4	A ⁴	A8	A ⁴	B2	B ⁰
98	0	A5	A ⁵	A10	A ⁵	B6	B ¹
99	0	A6	A ⁶	A12	A ⁶	B10	B ²
100	0	A7	A ⁷	A14	A ⁷	B12	B ³

*This pin is input only.

ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
1	0	GND	-
2	0	TDI	-
3	0	VCCO (Bank 0)	-
4	0	B0	B ⁰
5	0	B1	B ¹
6	0	B2	B ²
7	0	B4	B ³
8	0	B5	B ⁴
9	0	B6	B ⁵
10	0	GND (Bank 0)	-
11	0	B8	B ⁶
12	0	B9	B ⁷
13	0	B10	B ⁸
14	0	B12	B ⁹
15	0	B13	B ¹⁰
16	0	B14	B ¹¹
17	0	VCCO (Bank 0)	-
18	0	C14	C ¹¹

ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP (Cont.)

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
129	-	VCC	-	VCC	-
130	0	A0/GOE0	A^0	A2/GOE0	A^1
131	0	A1	A^1	A4	A^2
132	0	A2	A^2	A6	A^3
133	0	A4	A^3	A8	A^4
134	0	A5	A^4	A10	A^5
135	0	A6	A^5	A12	A^6
136	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
137	0	GND (Bank 0)	-	GND (Bank 0)	-
138	0	A8	A^6	B2	B^1
139	0	A9	A^7	B4	B^2
140	0	A10	A^8	B6	B^3
141	0	A12	A^9	B8	B^4
142	0	A13	A^10	B10	B^5
143	0	A14	A^11	B12	B^6
144	0	NC ²	-	I ²	-

1. For device migration considerations, these NC pins are GND pins for I/O banks in ispMACH 4128V devices.

2. For device migration considerations, these NC pins are input signal pins in ispMACH 4256V devices.

ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections: 176-Pin TQFP

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	NC	-	NC	-	NC	-
2	-	GND	-	GND	-	GND	-
3	-	TDI	-	TDI	-	TDI	-
4	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
5	0	C14	C^7	C14	C^7	C14	C^7
6	0	C12	C^6	C12	C^6	C12	C^6
7	0	C10	C^5	C10	C^5	C10	C^5
8	0	C8	C^4	C8	C^4	C8	C^4
9	0	C6	C^3	C6	C^3	C6	C^3
10	0	C4	C^2	C4	C^2	C4	C^2
11	0	C2	C^1	C2	C^1	C2	C^1
12	0	C0	C^0	C0	C^0	C0	C^0
13	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
14	0	D14	D^7	E14	E^7	G14	G^7
15	0	D12	D^6	E12	E^6	G12	G^6
16	0	D10	D^5	E10	E^5	G10	G^5
17	0	D8	D^4	E8	E^4	G8	G^4
18	0	D6	D^3	E6	E^3	G6	G^3

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
19	0	D4	D [^] 2	E4	E [^] 2	G4	G [^] 2
20	0	D2	D [^] 1	E2	E [^] 1	G2	G [^] 1
21	0	D0	D [^] 0	E0	E [^] 0	G0	G [^] 0
22	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
23	0	E0	E [^] 0	H0	H [^] 0	J0	J [^] 0
24	0	E2	E [^] 1	H2	H [^] 1	J2	J [^] 1
25	0	E4	E [^] 2	H4	H [^] 2	J4	J [^] 2
26	0	E6	E [^] 3	H6	H [^] 3	J6	J [^] 3
27	0	E8	E [^] 4	H8	H [^] 4	J8	J [^] 4
28	0	E10	E [^] 5	H10	H [^] 5	J10	J [^] 5
29	0	E12	E [^] 6	H12	H [^] 6	J12	J [^] 6
30	0	E14	E [^] 7	H14	H [^] 7	J14	J [^] 7
31	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
32	0	F0	F [^] 0	J0	J [^] 0	N0	N [^] 0
33	0	F2	F [^] 1	J2	J [^] 1	N2	N [^] 1
34	0	F4	F [^] 2	J4	J [^] 2	N4	N [^] 2
35	0	F6	F [^] 3	J6	J [^] 3	N6	N [^] 3
36	0	F8	F [^] 4	J8	J [^] 4	N8	N [^] 4
37	0	F10	F [^] 5	J10	J [^] 5	N10	N [^] 5
38	0	F12	F [^] 6	J12	J [^] 6	N12	N [^] 6
39	0	F14	F [^] 7	J14	J [^] 7	N14	N [^] 7
40	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
41	-	TCK	-	TCK	-	TCK	-
42	-	VCC	-	VCC	-	VCC	-
43	-	NC	-	NC	-	NC	-
44	-	NC	-	NC	-	NC	-
45	-	NC	-	NC	-	NC	-
46	-	GND	-	GND (Bank 0)	-	GND	-
47	0	G14	G [^] 7	K14	K [^] 7	O14	O [^] 7
48	0	G12	G [^] 6	K12	K [^] 6	O12	O [^] 6
49	0	G10	G [^] 5	K10	K [^] 5	O10	O [^] 5
50	0	G8	G [^] 4	K8	K [^] 4	O8	O [^] 4
51	0	G6	G [^] 3	K6	K [^] 3	O6	O [^] 3
52	0	G4	G [^] 2	K4	K [^] 2	O4	O [^] 2
53	0	G2	G [^] 1	K2	K [^] 1	O2	O [^] 1
54	0	G0	G [^] 0	K0	K [^] 0	O0	O [^] 0
55	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
56	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
57	0	H14	H [^] 7	L14	L [^] 7	P14	P [^] 7
58	0	H12	H [^] 6	L12	L [^] 6	P12	P [^] 6
59	0	H10	H [^] 5	L10	L [^] 5	P10	P [^] 5

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:
256-Ball ftBGA/fpBGA**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
-	-	-	-	-	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
C3	-	TDI	-	TDI	-	TDI	-	TDI	-
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B1	0	C14	C ⁷	C14	C ⁹	C14	C ⁷	C14	C ⁷
F5	0	C12	C ⁶	C12	C ⁸	C12	C ⁶	C12	C ⁶
D3	0	C10	C ⁵	C10	C ⁷	C10	C ⁵	C10	C ⁵
C1	0	C8	C ⁴	C9	C ⁶	C8	C ⁴	C8	C ⁴
C2	0	C6	C ³	C8	C ⁵	C6	C ³	C6	C ³
E3	0	C4	C ²	C6	C ⁴	C4	C ²	C4	C ²
D2	0	C2	C ¹	C4	C ³	C2	C ¹	C2	C ¹
F6	0	C0	C ⁰	C2	C ²	C0	C ⁰	C0	C ⁰
D1	0	NC	-	C1	C ¹	F6	F ³	H0	H ⁰
E2	0	NC	-	C0	C ⁰	F4	F ²	H4	H ¹
E4	0	NC	-	NC	-	D6	D ³	F4	F ²
G5	0	NC	-	NC	-	D4	D ²	F6	F ³
E1	0	NC	-	NC	-	NC	-	F8	F ⁴
-	0	-	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
F2	0	NC	-	NC	-	NC	-	F10	F ⁵
F1	0	NC	-	NC	-	D2	D ¹	F12	F ⁶
G1	0	NC	-	NC	-	D0	D ⁰	F14	F ⁷
G6	0	NC	-	D14	D ⁹	F2	F ¹	H8	H ²
G4	0	NC	-	D12	D ⁸	F0	F ⁰	H12	H ³
H6	0	D14	D ⁷	D10	D ⁷	E14	E ⁷	G14	G ⁷
G3	0	D12	D ⁶	D9	D ⁶	E12	E ⁶	G12	G ⁶
H5	0	D10	D ⁵	D8	D ⁵	E10	E ⁵	G10	G ⁵
G2	0	D8	D ⁴	D6	D ⁴	E8	E ⁴	G8	G ⁴
H1	0	D6	D ³	D4	D ³	E6	E ³	G6	G ³
H2	0	D4	D ²	D2	D ²	E4	E ²	G4	G ²
H3	0	D2	D ¹	D1	D ¹	E2	E ¹	G2	G ¹
H4	0	D0	D ⁰	D0	D ⁰	E0	E ⁰	G0	G ⁰
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	-	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
J4	0	E0	E ⁰	E0	E ⁰	H0	H ⁰	J0	J ⁰
J3	0	E2	E ¹	E1	E ¹	H2	H ¹	J2	J ¹
J2	0	E4	E ²	E2	E ²	H4	H ²	J4	J ²
J1	0	E6	E ³	E4	E ³	H6	H ³	J6	J ³
K1	0	E8	E ⁴	E6	E ⁴	H8	H ⁴	J8	J ⁴
J5	0	E10	E ⁵	E8	E ⁵	H10	H ⁵	J10	J ⁵
K2	0	E12	E ⁶	E9	E ⁶	H12	H ⁶	J12	J ⁶

ispMACH 4000C (1.8V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128C	LC4128C-27T128C	128	1.8	2.7	TQFP	128	92	C
	LC4128C-5T128C	128	1.8	5	TQFP	128	92	C
	LC4128C-75T128C	128	1.8	7.5	TQFP	128	92	C
	LC4128C-27T100C	128	1.8	2.7	TQFP	100	64	C
	LC4128C-5T100C	128	1.8	5	TQFP	100	64	C
	LC4128C-75T100C	128	1.8	7.5	TQFP	100	64	C
LC4256C	LC4256C-3FT256AC	256	1.8	3	ftBGA	256	128	C
	LC4256C-5FT256AC	256	1.8	5	ftBGA	256	128	C
	LC4256C-75FT256AC	256	1.8	7.5	ftBGA	256	128	C
	LC4256C-3FT256BC	256	1.8	3	ftBGA	256	160	C
	LC4256C-5FT256BC	256	1.8	5	ftBGA	256	160	C
	LC4256C-75FT256BC	256	1.8	7.5	ftBGA	256	160	C
	LC4256C-3F256AC ¹	256	1.8	3	fpBGA	256	128	C
	LC4256C-5F256AC ¹	256	1.8	5	fpBGA	256	128	C
	LC4256C-75F256AC ¹	256	1.8	7.5	fpBGA	256	128	C
	LC4256C-3F256BC ¹	256	1.8	3	fpBGA	256	160	C
	LC4256C-5F256BC ¹	256	1.8	5	fpBGA	256	160	C
	LC4256C-75F256BC ¹	256	1.8	7.5	fpBGA	256	160	C
	LC4256C-3T176C	256	1.8	3	TQFP	176	128	C
	LC4256C-5T176C	256	1.8	5	TQFP	176	128	C
	LC4256C-75T176C	256	1.8	7.5	TQFP	176	128	C
	LC4256C-3T100C	256	1.8	3	TQFP	100	64	C
	LC4256C-5T100C	256	1.8	5	TQFP	100	64	C
	LC4256C-75T100C	256	1.8	7.5	TQFP	100	64	C
LC4384C	LC4384C-35FT256C	384	1.8	3.5	ftBGA	256	192	C
	LC4384C-5FT256C	384	1.8	5	ftBGA	256	192	C
	LC4384C-75FT256C	384	1.8	7.5	ftBGA	256	192	C
	LC4384C-35F256C ¹	384	1.8	3.5	fpBGA	256	192	C
	LC4384C-5F256C ¹	384	1.8	5	fpBGA	256	192	C
	LC4384C-75F256C ¹	384	1.8	7.5	fpBGA	256	192	C
	LC4384C-35T176C	384	1.8	3.5	TQFP	176	128	C
	LC4384C-5T176C	384	1.8	5	TQFP	176	128	C
	LC4384C-75T176C	384	1.8	7.5	TQFP	176	128	C
LC4512C	LC4512C-35FT256C	512	1.8	3.5	ftBGA	256	208	C
	LC4512C-5FT256C	512	1.8	5	ftBGA	256	208	C
	LC4512C-75FT256C	512	1.8	7.5	ftBGA	256	208	C
	LC4512C-35F256C ¹	512	1.8	3.5	fpBGA	256	208	C
	LC4512C-5F256C ¹	512	1.8	5	fpBGA	256	208	C
	LC4512C-75F256C ¹	512	1.8	7.5	fpBGA	256	208	C
	LC4512C-35T176C	512	1.8	3.5	TQFP	176	128	C
	LC4512C-5T176C	512	1.8	5	TQFP	176	128	C
	LC4512C-75T176C	512	1.8	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000C (1.8V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4384C	LC4384C-5FT256I	384	1.8	5	ftBGA	256	192	I
	LC4384C-75FT256I	384	1.8	7.5	ftBGA	256	192	I
	LC4384C-10FT256I	384	1.8	10	ftBGA	256	192	I
	LC4384C-5F256I ¹	384	1.8	5	fpBGA	256	192	I
	LC4384C-75F256I ¹	384	1.8	7.5	fpBGA	256	192	I
	LC4384C-10F256I ¹	384	1.8	10	fpBGA	256	192	I
	LC4384C-5T176I	384	1.8	5	TQFP	176	128	I
	LC4384C-75T176I	384	1.8	7.5	TQFP	176	128	I
	LC4384C-10T176I	384	1.8	10	TQFP	176	128	I
LC4512C	LC4512C-5FT256I	512	1.8	5	ftBGA	256	208	I
	LC4512C-75FT256I	512	1.8	7.5	ftBGA	256	208	I
	LC4512C-10FT256I	512	1.8	10	ftBGA	256	208	I
	LC4512C-5F256I ¹	512	1.8	5	fpBGA	256	208	I
	LC4512C-75F256I ¹	512	1.8	7.5	fpBGA	256	208	I
	LC4512C-10F256I ¹	512	1.8	10	fpBGA	256	208	I
	LC4512C-5T176I	512	1.8	5	TQFP	176	128	I
	LC4512C-75T176I	512	1.8	7.5	TQFP	176	128	I
	LC4512C-10T176I	512	1.8	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000B (2.5V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-25T48C	32	2.5	2.5	TQFP	48	32	C
	LC4032B-5T48C	32	2.5	5	TQFP	48	32	C
	LC4032B-75T48C	32	2.5	7.5	TQFP	48	32	C
	LC4032B-25T44C	32	2.5	2.5	TQFP	44	30	C
	LC4032B-5T44C	32	2.5	5	TQFP	44	30	C
	LC4032B-75T44C	32	2.5	7.5	TQFP	44	30	C
LC4064B	LC4064B-25T100C	64	2.5	2.5	TQFP	100	64	C
	LC4064B-5T100C	64	2.5	5	TQFP	100	64	C
	LC4064B-75T100C	64	2.5	7.5	TQFP	100	64	C
	LC4064B-25T48C	64	2.5	2.5	TQFP	48	32	C
	LC4064B-5T48C	64	2.5	5	TQFP	48	32	C
	LC4064B-75T48C	64	2.5	7.5	TQFP	48	32	C
	LC4064B-25T44C	64	2.5	2.5	TQFP	44	30	C
	LC4064B-5T44C	64	2.5	5	TQFP	44	30	C
	LC4064B-75T44C	64	2.5	7.5	TQFP	44	30	C
LC4128B	LC4128B-27T128C	128	2.5	2.7	TQFP	128	92	C
	LC4128B-5T128C	128	2.5	5	TQFP	128	92	C
	LC4128B-75T128C	128	2.5	7.5	TQFP	128	92	C
	LC4128B-27T100C	128	2.5	2.7	TQFP	100	64	C
	LC4128B-5T100C	128	2.5	5	TQFP	100	64	C
	LC4128B-75T100C	128	2.5	7.5	TQFP	100	64	C

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4512V	LC4512V-35FT256C	512	3.3	3.5	ftBGA	256	208	C
	LC4512V-5FT256C	512	3.3	5	ftBGA	256	208	C
	LC4512V-75FT256C	512	3.3	7.5	ftBGA	256	208	C
	LC4512V-35F256C ¹	512	3.3	3.5	fpBGA	256	208	C
	LC4512V-5F256C ¹	512	3.3	5	fpBGA	256	208	C
	LC4512V-75F256C ¹	512	3.3	7.5	fpBGA	256	208	C
	LC4512V-35T176C	512	3.3	3.5	TQFP	176	128	C
	LC4512V-5T176C	512	3.3	5	TQFP	176	128	C
	LC4512V-75T176C	512	3.3	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000V (3.3V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5T48I	32	3.3	5	TQFP	48	32	I
	LC4032V-75T48I	32	3.3	7.5	TQFP	48	32	I
	LC4032V-10T48I	32	3.3	10	TQFP	48	32	I
	LC4032V-5T44I	32	3.3	5	TQFP	44	30	I
	LC4032V-75T44I	32	3.3	7.5	TQFP	44	30	I
	LC4032V-10T44I	32	3.3	10	TQFP	44	30	I
LC4064V	LC4064V-5T100I	64	3.3	5	TQFP	100	64	I
	LC4064V-75T100I	64	3.3	7.5	TQFP	100	64	I
	LC4064V-10T100I	64	3.3	10	TQFP	100	64	I
	LC4064V-5T48I	64	3.3	5	TQFP	48	32	I
	LC4064V-75T48I	64	3.3	7.5	TQFP	48	32	I
	LC4064V-10T48I	64	3.3	10	TQFP	48	32	I
	LC4064V-5T44I	64	3.3	5	TQFP	44	30	I
	LC4064V-75T44I	64	3.3	7.5	TQFP	44	30	I
	LC4064V-10T44I	64	3.3	10	TQFP	44	30	I
LC4128V	LC4128V-5T144I	128	3.3	5	TQFP	144	96	I
	LC4128V-75T144I	128	3.3	7.5	TQFP	144	96	I
	LC4128V-10T144I	128	3.3	10	TQFP	144	96	I
	LC4128V-5T128I	128	3.3	5	TQFP	128	92	I
	LC4128V-75T128I	128	3.3	7.5	TQFP	128	92	I
	LC4128V-10T128I	128	3.3	10	TQFP	128	92	I
	LC4128V-5T100I	128	3.3	5	TQFP	100	64	I
	LC4128V-75T100I	128	3.3	7.5	TQFP	100	64	I
	LC4128V-10T100I	128	3.3	10	TQFP	100	64	I

ispMACH 4000C (1.8V) Lead-Free Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4064C	LC4064C-25TN100C	64	1.8	2.5	Lead-free TQFP	100	64	C
	LC4064C-5TN100C	64	1.8	5	Lead-free TQFP	100	64	C
	LC4064C-75TN100C	64	1.8	7.5	Lead-free TQFP	100	64	C
	LC4064C-25TN48C	64	1.8	2.5	Lead-free TQFP	48	32	C
	LC4064C-5TN48C	64	1.8	5	Lead-free TQFP	48	32	C
	LC4064C-75TN48C	64	1.8	7.5	Lead-free TQFP	48	32	C
	LC4064C-25TN44C	64	1.8	2.5	Lead-free TQFP	44	30	C
	LC4064C-5TN44C	64	1.8	5	Lead-free TQFP	44	30	C
	LC4064C-75TN44C	64	1.8	7.5	Lead-free TQFP	44	30	C
LC4128C	LC4128C-27TN128C	128	1.8	2.7	Lead-free TQFP	128	92	C
	LC4128C-5TN128C	128	1.8	5	Lead-free TQFP	128	92	C
	LC4128C-75TN128C	128	1.8	7.5	Lead-free TQFP	128	92	C
	LC4128C-27TN100C	128	1.8	2.7	Lead-free TQFP	100	64	C
	LC4128C-5TN100C	128	1.8	5	Lead-free TQFP	100	64	C
	LC4128C-75TN100C	128	1.8	7.5	Lead-free TQFP	100	64	C
LC4256C	LC4256C-3FTN256AC	256	1.8	3	Lead-free ftBGA	256	128	C
	LC4256C-5FTN256AC	256	1.8	5	Lead-free ftBGA	256	128	C
	LC4256C-75FTN256AC	256	1.8	7.5	Lead-free ftBGA	256	128	C
	LC4256C-3FTN256BC	256	1.8	3	Lead-free ftBGA	256	160	C
	LC4256C-5FTN256BC	256	1.8	5	Lead-free ftBGA	256	160	C
	LC4256C-75FTN256BC	256	1.8	7.5	Lead-free ftBGA	256	160	C
	LC4256C-3FN256AC ¹	256	1.8	3	Lead-free fpBGA	256	128	C
	LC4256C-5FN256AC ¹	256	1.8	5	Lead-free fpBGA	256	128	C
	LC4256C-75FN256AC ¹	256	1.8	7.5	Lead-free fpBGA	256	128	C
	LC4256C-3FN256BC ¹	256	1.8	3	Lead-free fpBGA	256	160	C
	LC4256C-5FN256BC ¹	256	1.8	5	Lead-free fpBGA	256	160	C
	LC4256C-75FN256BC ¹	256	1.8	7.5	Lead-free fpBGA	256	160	C
	LC4256C-3TN176C	256	1.8	3	Lead-free TQFP	176	128	C
	LC4256C-5TN176C	256	1.8	5	Lead-free TQFP	176	128	C
	LC4256C-75TN176C	256	1.8	7.5	Lead-free TQFP	176	128	C
	LC4256C-3TN100C	256	1.8	3	Lead-free TQFP	100	64	C
	LC4256C-5TN100C	256	1.8	5	Lead-free TQFP	100	64	C
	LC4256C-75TN100C	256	1.8	7.5	Lead-free TQFP	100	64	C
LC4384C	LC4384C-35FTN256C	384	1.8	3.5	Lead-free ftBGA	256	192	C
	LC4384C-5FTN256C	384	1.8	5	Lead-free ftBGA	256	192	C
	LC4384C-75FTN256C	384	1.8	7.5	Lead-free ftBGA	256	192	C
	LC4384C-35FN256C ¹	384	1.8	3.5	Lead-free fpBGA	256	192	C
	LC4384C-5FN256C ¹	384	1.8	5	Lead-free fpBGA	256	192	C
	LC4384C-75FN256C ¹	384	1.8	7.5	Lead-free fpBGA	256	192	C
	LC4384C-35TN176C	384	1.8	3.5	Lead-free TQFP	176	128	C
	LC4384C-5TN176C	384	1.8	5	Lead-free TQFP	176	128	C
	LC4384C-75TN176C	384	1.8	7.5	Lead-free TQFP	176	128	C